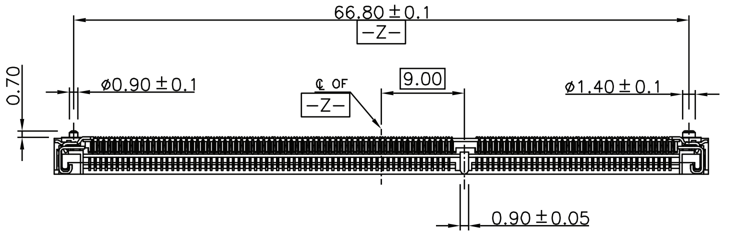
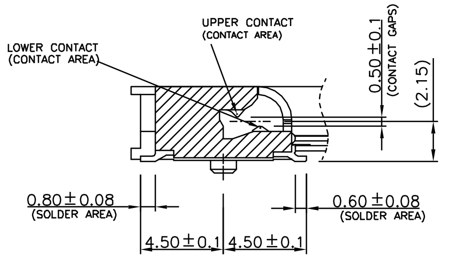
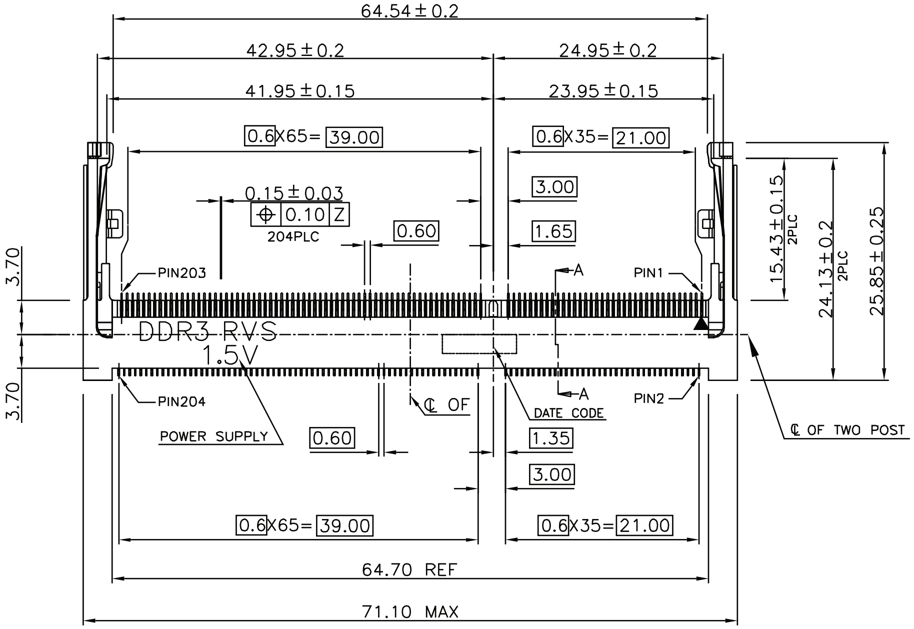
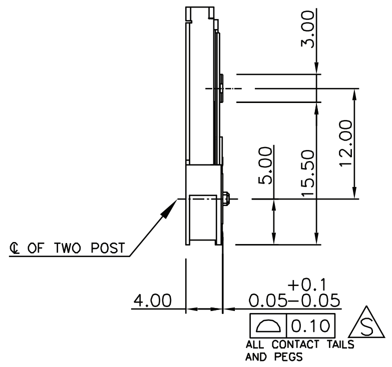
NOTES:
1. Recommended Reflow
Temperature 260˚C (5 Sec.)
2. Voltage Rating: 25 VAC
3. Current Rating: 0.5 A
4. Temperature Rating: -55 C to 85 C





CROSS SECTIONAL A-A





HOW TO ORDER:

B 0 3 0 - 2 0 4 3 - C 1 X X - Z

NUMBER OF CONTACTS:
204

KEY TYPE / VOLTAGE OPTION :
3 - 1.5V TYPE

HEIGHT OPTION
C - 4.0mm

ORIENTATION:
1 - Reverse

PLATING OPTIONS:
2 - Au FLASH
6 - 15u" Au

PACKAGING:
0 - Tray
1 - Tape & Reel (Normal)
2 - Tape & Reel (Reverse)

RoHS
COMPLIANT

MATERIAL:
CONTACT PLATING: Specified Au Thickness in Contact Area
Au Flash on Solder Tails; 50u" Nickel Sub Plate
Nickel Sub Plate (80"m min)
HOUSING: High Temp Thermo Plastic UL94V-0, Black
METAL LATCH: Stainless Steel
FLOATING LATCH: Stainless Steel
FIXED LATCH: Stainless Steel
CONTACT: Copper Alloy

Rev	Description	Drawn	Checked	Approved	Date
0	Issued	B.S.	S.M.	S.M.	09/02/10

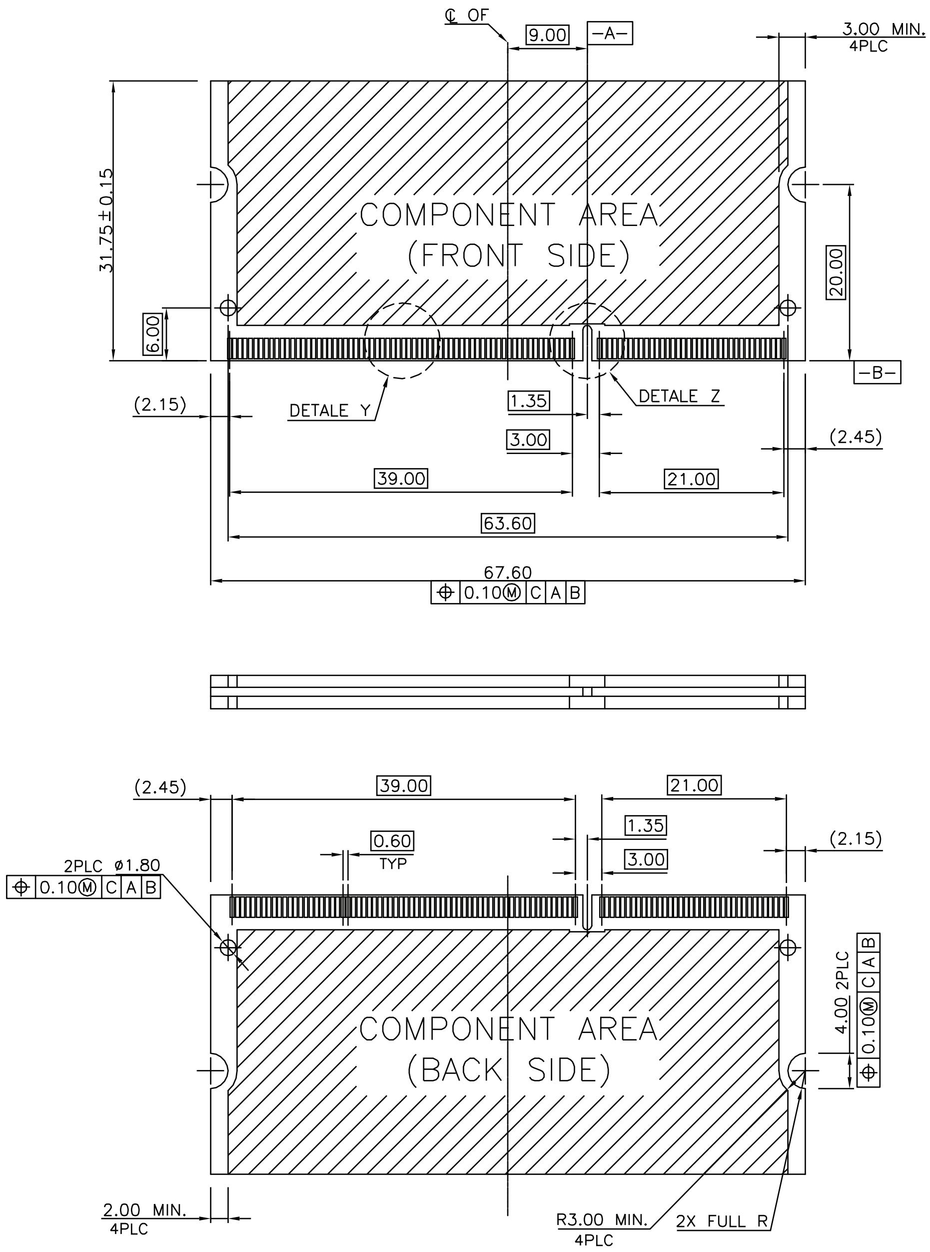
SMP TECHNOLOGY, INC.

DDR SO DIMM Socket, 204 Position, 1.5 Volt

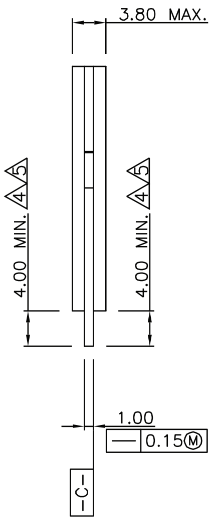
Reverse Orientation, Right Angle, 4.0mm Height, Type 2

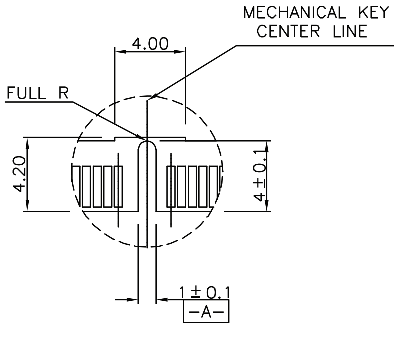
TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm

P/N: B030-2043-C1XX-Z

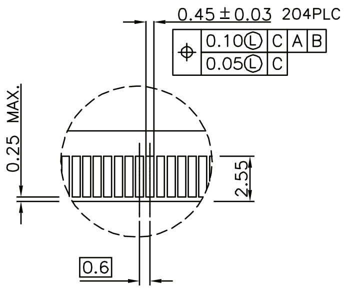


RECOMMENDED MATING P.C.B CONFIGURATION





DETAIL Z



DETAIL Y

NOTE:
1. TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE SPECIFIED.
2. P.C.BOARD THICKNESS APPLIES ACROSS TABS
AND INCLUDES PLATING AND/OR MENTAIZATION.
3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER ON PLATING 0.002MIN.
4. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE.
PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.
5. BORDER OF COMPONENT AREA.

SMP TECHNOLOGY, INC.

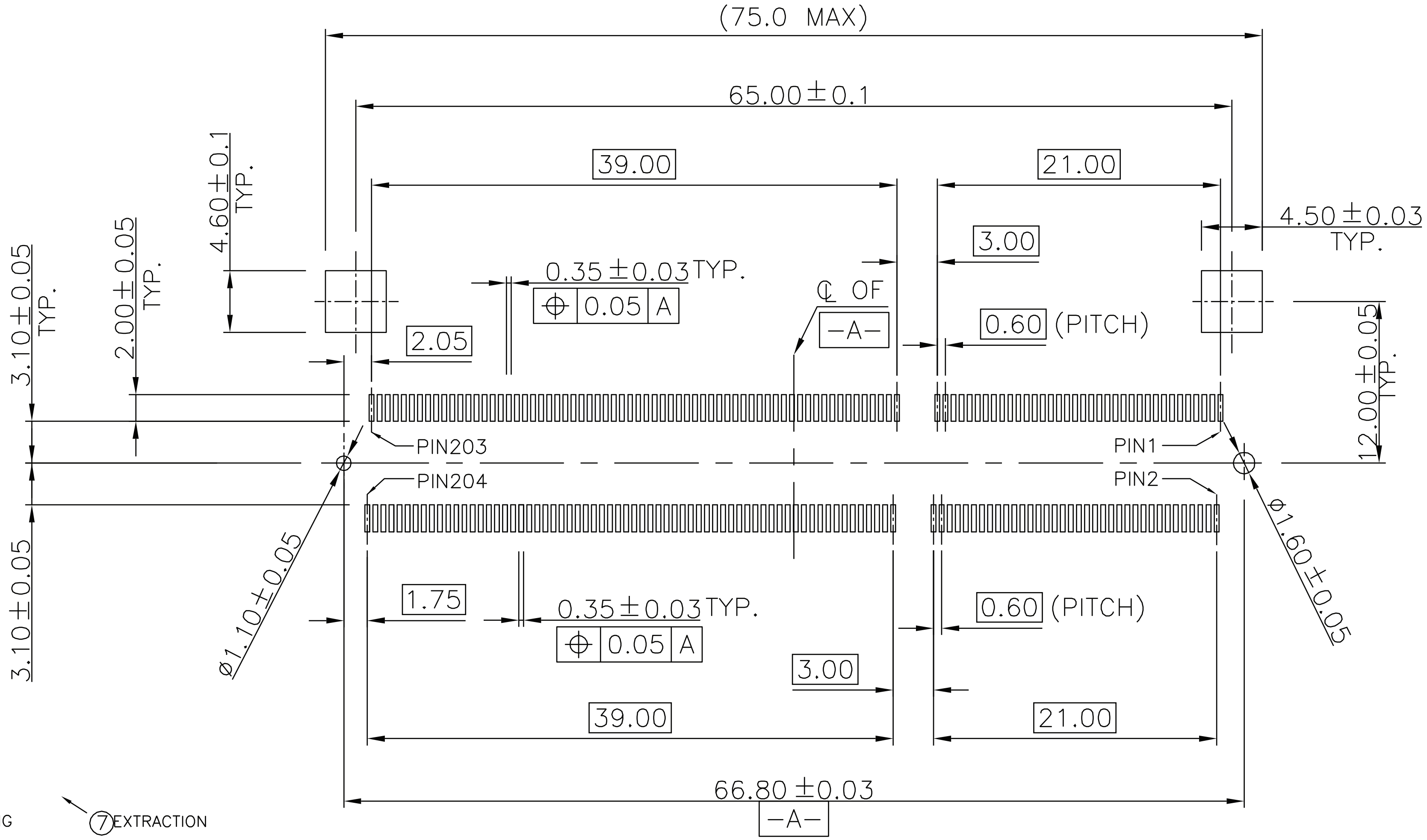
DDR SO DIMM Socket, 204 Position, 1.5 Volt

Reverse Orientation, Right Angle, 4.0mm Height, Type 2

P/N: B030-2043-C1XX-Z

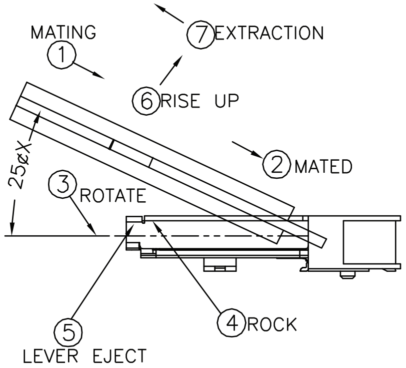
Pg: 2 of 5

TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm



RECOMMENDED PCB LAYOUT

THICKNESS: 1.6±0.05mm



HOW TO MATE AND UNMATE

MATE: ①→④

UNMATE: ⑤→⑦

SMP TECHNOLOGY, INC.

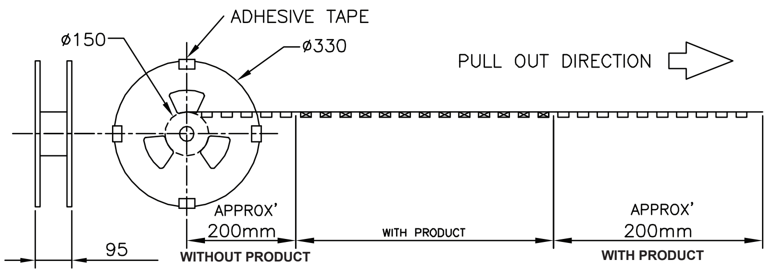
DDR SO DIMM Socket, 204 Position, 1.5 Volt

Reverse Orientation, Right Angle, 4.0mm Height, Type 2

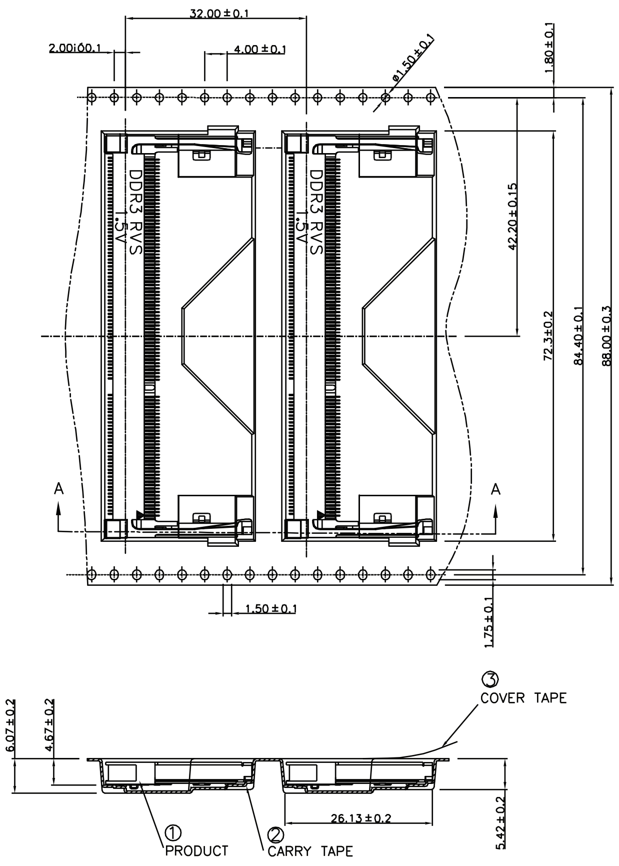
P/N: B030-2043-C1XX-Z

Pg: 3 of 5

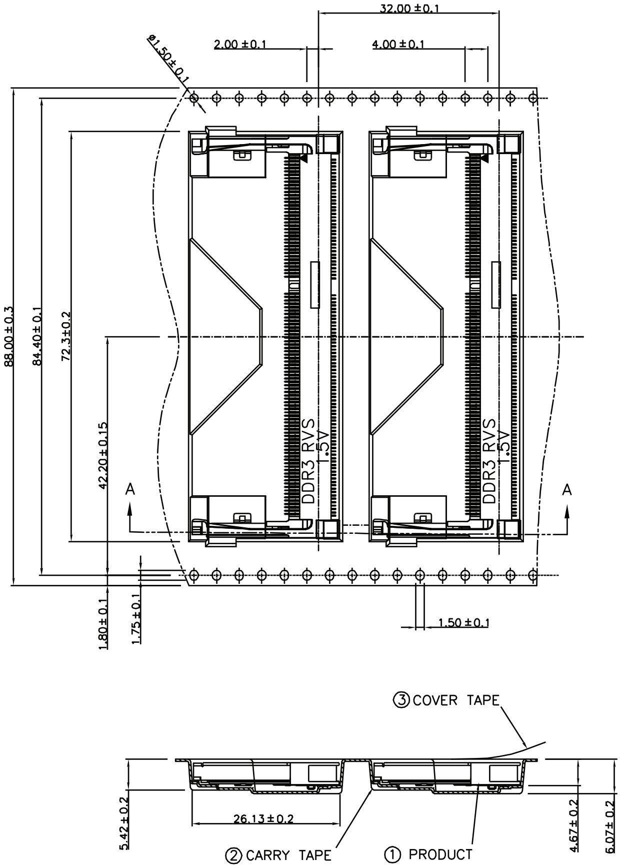
TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm



NOTES:
1. PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND
MUST MEET CONTROLLED SUBSTANCES SPEC PER WI-PB-22.
* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED : 5 PPM.
* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED : 100 PPM (COMBINED)
2. CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONETS MUST MEET
THE REQUIREMENTS DEFINED PER EIA-481-B.
3. DIMENSION :
3.1 REEL: H =95, øA=330
3.2 SHIPPING CARTON : L = 335, W =335, H = 248
4. QUANTITY :
4.1 PRIMARY PACKAGING : 300PCS / REEL
4.2 SECONDARY PACKAGING : 2 REELS / CARTON (600PCS)
5. WEIGHT :
5.1 NET WEIGHT : 1.77 Kg / REEL, 3.53 Kg / CARTON.
5.2 GROOS WEIGHT : 2.03 Kg / REEL, 4.05 Kg / CARTON
6. PEELING RESISTANCE : 0.1~0.7N (10.2gf ~ 71.4gf)
7. PEELING SPEED : 300mm / MINUTE.



Section A-A
Packaging Direction: Tape & Reel Normal



Section A-A
Packaging Direction: Tape & Reel Reverse

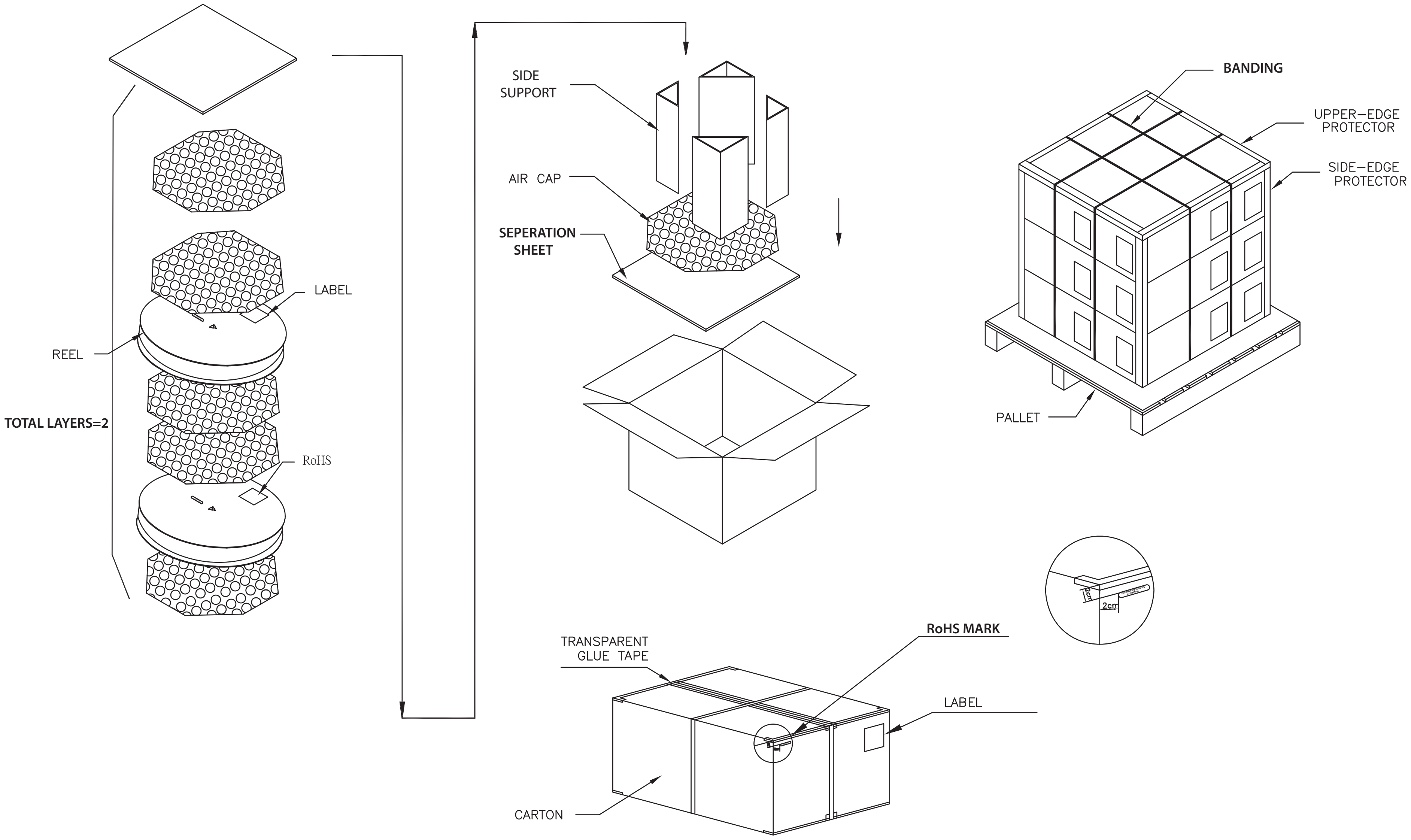
SMP TECHNOLOGY, INC.

DDR SO DIMM Socket, 204 Position, 1.5 Volt

Reverse Orientation, Right Angle, 4.0mm Height, Type 2

TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm

P/N: B030-2043-C1XX-Z



SMP TECHNOLOGY, INC.

DDR SO DIMM Socket, 204 Position, 1.5 Volt

Reverse Orientation, Right Angle, 4.0mm Height, Type 2

TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm

P/N: B030-2043-C1XX-Z